



Form PTO 1449 (Modified)		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		ATTY DOCKET NO. 291619US0PCT		SERIAL NO. 10/581,111	
LIST OF REFERENCES CITED BY APPLICANT				APPLICANT Hubert MORICEAU, et al.			
				FILING DATE May 31, 2006		GROUP	
<b>U.S. PATENT DOCUMENTS</b>							
EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE
/S.J.N./	AA	2003/211705	11/13/03	TONG, Qin-Yi et al.			
/S.J.N./	AB	4 983 251	01/08/91	HAISMA, Jan et al.			
	AC	2003/0211705					
	AD						
	AE						
	AF						
	AG						
	AH						
	AI						
	AJ						
	AK						
	AL						
	AM						
	AN						
<b>FOREIGN PATENT DOCUMENTS</b>							
		DOCUMENT NUMBER	DATE	COUNTRY	TRANSLATION		
					YES	NO	
/S.J.N./	AO	2 787 919	06/30/00	FR(with English abstract)		NO	
/S.J.N./	AP	2 796 491	01/19/01	FR(equivalent of US 6 821 376)		NO	
	AQ						
	AR						
	AS						
	AT						
	AU						
	AV						
<b>OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, etc.)</b>							
/S.J.N./	AW	TONG, Q.-Y. et al., "Semiconductor Wafer Bonding, Science and Technology", The Electrochemical Society Series, Wiley-Interscience, John Wiley and Sons, Inc., New York (1999).					
/S.J.N./	AX	MORICEAU, H. et al., "The Bonding Energy Control: An Original Way To Debondable Substrates", Conference of International Electrochemical Society, Paris, June 2003.					
	AY						
	AZ					<input type="checkbox"/> Additional References sheet(s) attached	
Examiner /Seahvosh Nikmanesh/					Date Considered 02/13/2008		
*Examiner: Initial if reference is considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.							

ALL REFERENCES CONSIDERED EXCEPT WHERE LINED THROUGH. /S.J.N./